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Jameco Part Number 759800

TL071, TL071A, TL071B, TL072 TL072A, TL072B, TL074, TL074A, TL074B LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS

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- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion
 ... 0.003% Typ

Low Noise

 $V_n = 18 \text{ nV}/\sqrt{\text{Hz}}$ Typ at f = 1 kHz

- High Input Impedance . . . JFET Input Stage
- Internal Frequency Compensation
- Latch-Up-Free Operation
- High Slew Rate . . . 13 V/μs Typ
- Common-Mode Input Voltage Range Includes V_{CC+}

description/ordering information

The JFET-input operational amplifiers in the TL07x series are similar to the TL08x series, with low input bias and offset currents and fast slew rate. The low harmonic distortion and low noise make the TL07x series ideally suited for high-fidelity and audio preamplifier applications. Each amplifier features JFET inputs (for high input impedance) coupled with bipolar output stages integrated on a single monolithic chip.

The C-suffix devices are characterized for operation from 0° C to 70° C. The I-suffix devices are characterized for operation from -40° C to 85° C. The M-suffix devices are characterized for operation over the full military temperature range of -55° C to 125° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



description/ordering information (continued)

ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKA	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		DDID (D)	Tube of 50	TL071CP	TL071CP
		PDIP (P)	Tube of 50	TL072CP	TL072CP
		PDIP (N)	Tube of 25	TL074CN	TL074CN
			Tube of 75	TL071CD	TI 0740
			Reel of 2500	TL071CDR	TL071C
		COIC (D)	Tube of 75	TL072CD	TI 0700
		SOIC (D)	Reel of 2500	TL072CDR	TL072C
	10 mV		Tube of 50	TL074CD	TI 0740
			Reel of 2500	TL074CDR	TL074C
		SOP (NS)	Reel of 2000	TL074CNSR	TL074
		000 (00)	Reel of 2000	TL071CPSR	TL071
		SOP (PS)	Reel of 2000	TL072CPSR	T072
			Reel of 2000	TL072CPWR	T072
		TSSOP (PW)	Tube of 90	TL074CPW	T074
			Reel of 2000	TL074CPWR	T074
		DDID (D)	Tube of 50	TL071ACP	TL071ACP
		PDIP (P)	Tube of 50	TL072ACP	TL072ACP
000 to 7000		PDIP (N)	Tube of 25	TL074ACN	TL074ACN
0°C to 70°C			Tube of 75	TL071ACD	07440
			Reel of 2500	TL071ACDR	071AC
	6 mV	0010 (D)	Tube of 75	TL072ACD	07040
		SOIC (D)	Reel of 2500	TL072ACDR	072AC
			Tube of 50	TL074ACD	TI 0744 C
			Reel of 2500	TL074ACDR	TL074AC
		SOP (PS)	Reel of 2000	TL072ACPSR	T072A
		SOP (NS)	Reel of 2000	TL074ACNSR	TL074A
		DDID (D)	Tube of 50	TL071BCP	TL071BCP
		PDIP (P)	Tube of 50	TL072BCP	TL072BCP
		PDIP (N)	Tube of 25	TL074BCN	TL074BCN
			Tube of 75	TL071BCD	071BC
	3 mV		Reel of 2500	TL071BCDR	UTIBO
	JIIIV	SOIC (D)	Tube of 75	TL072BCD	072BC
		3010 (D)	Reel of 2500	TL072BCDR	UZDC
			Tube of 50	TL074BCD	TI 074BC
			Reel of 2500	TL074BCDR	TL074BC
		SOP (NS)	Reel of 2000	TL074BCNSR	TL074B

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



description/ordering information (continued)

ORDERING INFORMATION

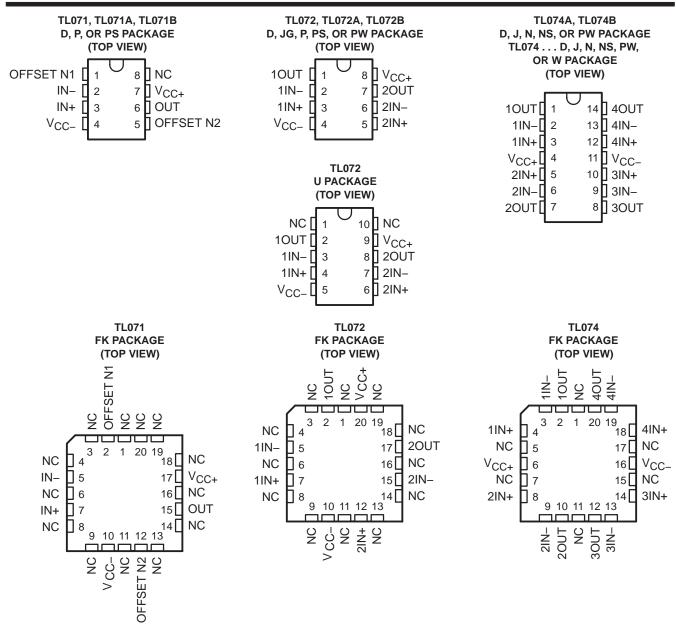
TA	V _{IO} max AT 25°C	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING					
		DDID (D)	Tube of 50	TL071IP	TL071IP					
		PDIP (P)	Tube of 50	TL072IP	TL072IP					
		PDIP (N)	Tube of 25	TL074IN	TL074IN					
			Tube of 75	TL071ID	TI 0741					
-40°C to 85°C	6 mV		Reel of 2500	TL071IDR	TL071I					
							0010 (D)	Tube of 75	TL072ID	TI 0701
		SOIC (D)	Reel of 2500	TL072IDR	TL072I					
			Tube of 50	TL074ID	TI 0741					
			Reel of 2500	TL074IDR	TL074I					
		CDIP (JG)	Tube of 50	TL072MJGB	TL072MJGB					
	6 mV	CFP (U)	Tube of 150	TL072MUB	TL072MUB					
−55°C to 125°C		LCCC (FK)	Tube of 55	TL072MFKB	TL072MFKB					
-55 0 10 125 0		CDIP (J)	Tube of 25	TL074MJB	TL074MJB					
	9 mV	CFP (W)	Tube of 25	TL074MWB	TL074MWB					
		LCCC (FK)	Tube of 55	TL074MFKB	TL074MFKB					

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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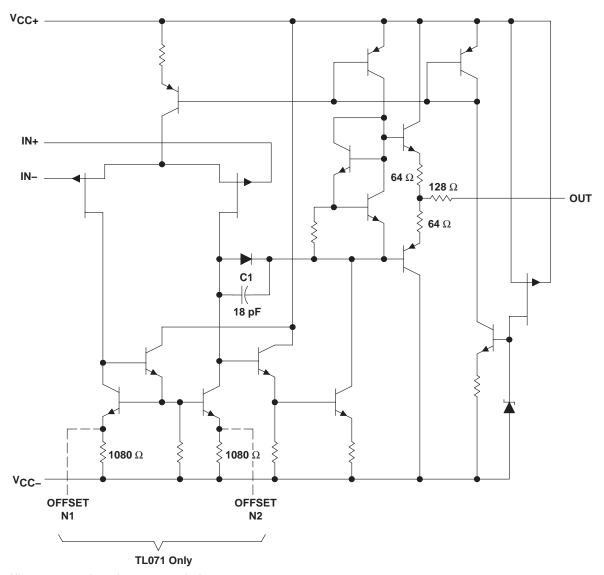
NC - No internal connection

symbols





schematic (each amplifier)



All component values shown are nominal.

COM	COMPONENT COUNT [†]										
COMPONENT TL071 TL072 TL074											
Resistors	11	22	44								
Transistors	14	28	56								
JFET	2	4	6								
Diodes	1	2	4								
Capacitors 1 2 4											
epi-FET	1	2	4								

[†] Includes bias and trim circuitry



TL071, TL071A, TL071B, TL072 TL072A, TL072B, TL074, TL074A, TL074B LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V _{CC+}		18 V
V _{CC}		–18 V
Differential input voltage, V _{ID} (see Note 2)		
Input voltage, V _I (see Notes 1 and 3)		
Duration of output short circuit (see Note 4)		
Package thermal impedance, θ _{JA} (see Notes 5 and 6):	D package (8 pin)	97°C/W
,	D package (14 pin)	86°C/W
	N package	
	NS package	
	P package	
	PS package	
	PW package (8 pin)	
	PW package (14 pin)	113°C/W
	U package	185°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8):	FK package	5.61°C/W
	J package	. 15.05°C/W
	JG package	14.5°C/W
	W package	. 14.65°C/W
Operating virtual junction temperature, T _J		150°C
Case temperature for 60 seconds: FK package		260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10		
Storage temperature range, T _{stg}		5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at IN+, with respect to IN-.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 8. The package thermal impedance is calculated in accordance with MIL-STD-883.



TL071, TL071A, TL071B, TL072 TL072A, TL072B, TL074, TL074A, TL074B LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS SLOS080J - SEPTEMBER 1978 - REVISED MARCH 2005

뜅

V/m/V

MHz

C

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mA

2.5

μV/°C

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nA

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200

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MAX

All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range is $T_A = 0^{\circ}C$ to $70^{\circ}C$ for $71^{\circ}C$, $71^{\circ}C$,

TL071, TL071A, TL071B, TL072 TL072A, TL072B, TL074, TL074A, TL074B LOW-NOISE JFET-INPUT OPERATIONAL AMPLIFIERS

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electrical characteristics, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS†	T _A ‡		TL071M TL072M			TL074M		UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V/	Innut offeet veltege	\/- 0	D- F0.0	25°C		3	6		3	9	mV
VIO	Input offset voltage	$V_{O} = 0,$	$R_S = 50 \Omega$	Full range			9			15	IIIV
αVio	Temperature coefficient of input offset voltage	V _O = 0,	$R_S = 50 \Omega$	Full range		18			18		μV/°C
1	Input offset current	\/- 0		25°C		5	100		5	100	pА
lio	input onset current	VO = 0		Full range			20			20	nA
l	Input bias current‡	V _O = 0		25°C		65	200		65	200	pA
IB	input bias current+	ΛQ = 0					50			50	nA
VICR	Common-mode input voltage range			25°C	±11	-12 to 15		±11	-12 to 15		V
		$R_L = 10 \text{ k}\Omega$		25°C	±12	±13.5		±12	±13.5		
VOM	Maximum peak output voltage swing	$R_L \ge 10 \text{ k}\Omega$		F. II	±12			±12			V
	voltage swilig	$R_L \ge 2 k\Omega$		Full range	±10			±10			
Δ	Large-signal differential	\/- \140\/	D. > 0 kO	25°C	35	200		35	200		V/mV
AVD	voltage amplification	$V_0 = \pm 10 \text{ V},$	K		15			15			V/IIIV
B ₁	Unity-gain bandwidth	T _A = 25°C				3			3		MHz
rį	Input resistance	T _A = 25°C				1012			1012		Ω
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR} m$ $V_{O} = 0$,		25°C	80	86		80	86		dB
k _{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC} = \pm 9 V t$ $V_{O} = 0$,		25°C	80	86		80	86		dB
Icc	Supply current (each amplifier)	V _O = 0,	No load	25°C		1.4	2.5		1.4	2.5	mA
V _{O1} /V _{O2}	Crosstalk attenuation	$A_{VD} = 100$		25°C		120			120		dB

[†] Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 4. Pulse techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.



[‡] All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range is $T_A = -55^{\circ}C$ to $125^{\circ}C$.

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operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

	DADAMETED	TEOT 00	TEST CONDITIONS				ALL OTHERS			LINUT
	PARAMETER	l lesi co	MIN TYP MAX		MAX	MIN	TYP	MAX	UNIT	
SR	Slew rate at unity gain	V _I = 10 V, C _L = 100 pF,	$R_L = 2 k\Omega$, See Figure 1	5	13		8	13		V/μs
_	Rise-time overshoot	V _I = 20 mV,	$R_L = 2 k\Omega$,		0.1			0.1		μs
τr	factor	$C_L = 100 pF$,	See Figure 1		20%			20%		
.,	Equivalent input noise	D 00.0	f = 1 kHz		18			18		nV/√ Hz
Vn	voltage	$R_S = 20 \Omega$	f = 10 Hz to 10 kHz		4			4		μV
In	Equivalent input noise current	$R_S = 20 \Omega$,	f = 1 kHz		0.01			0.01		pA/√ Hz
THD	Total harmonic distortion	$V_{l}rms = 6 V,$ $R_{L} \ge 2 k\Omega,$ $f = 1 kHz$	AVD = 1, $RS \le 1 \text{ k}\Omega,$		0.003 %		().003%		-

PARAMETER MEASUREMENT INFORMATION

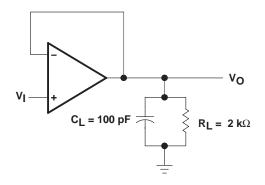


Figure 1. Unity-Gain Amplifier

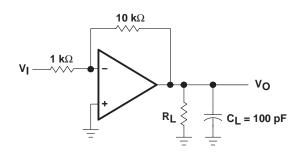


Figure 2. Gain-of-10 Inverting Amplifier

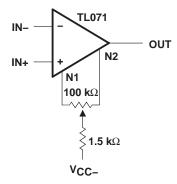


Figure 3. Input Offset-Voltage Null Circuit

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TYPICAL CHARACTERISTICS

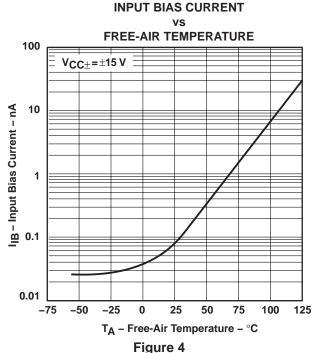
Table of Graphs

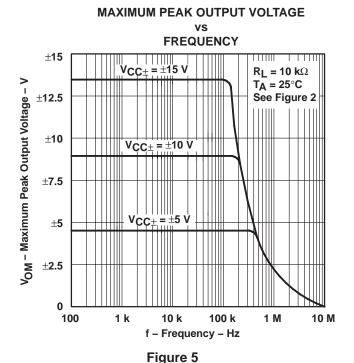
			FIGURE
I _{IB}	Input bias current	vs Free-air temperature	4
V _{OM}	Maximum output voltage	vs Frequency vs Free-air temperature vs Load resistance vs Supply voltage	5, 6, 7 8 9 10
A _{VD}	Large-signal differential voltage amplification	vs Free-air temperature vs Frequency	11 12
	Phase shift	vs Frequency	12
	Normalized unity-gain bandwidth	vs Free-air temperature	13
	Normalized phase shift	vs Free-air temperature	13
CMRR	Common-mode rejection ratio	vs Free-air temperature	14
Icc	Supply current	vs Supply voltage vs Free-air temperature	15 16
PD	Total power dissipation	vs Free-air temperature	17
	Normalized slew rate	vs Free-air temperature	18
Vn	Equivalent input noise voltage	vs Frequency	19
THD	Total harmonic distortion	vs Frequency	20
	Large-signal pulse response	vs Time	21
٧o	Output voltage	vs Elapsed time	22



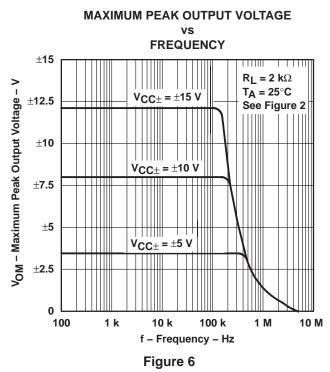
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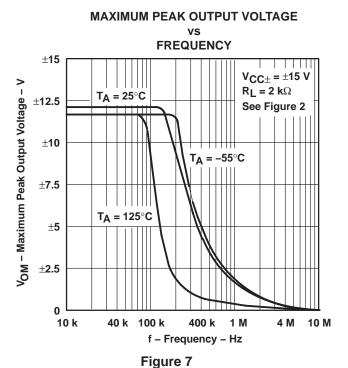
TYPICAL CHARACTERISTICS[†]





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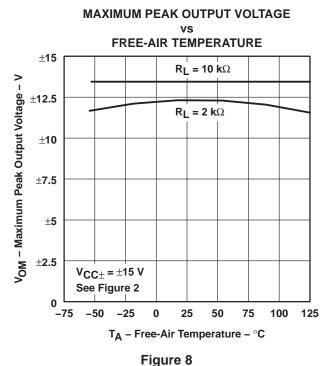


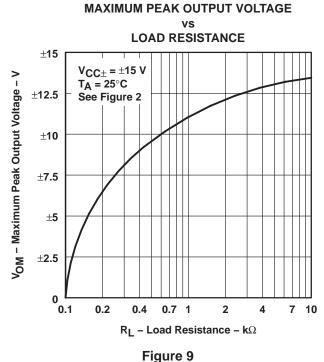


[†]Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

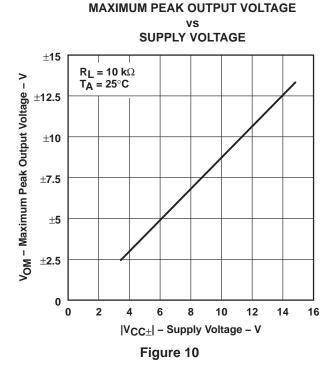


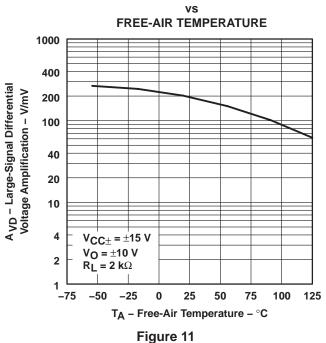
TYPICAL CHARACTERISTICS[†]











[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



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TYPICAL CHARACTERISTICS[†]

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION AND PHASE SHIFT

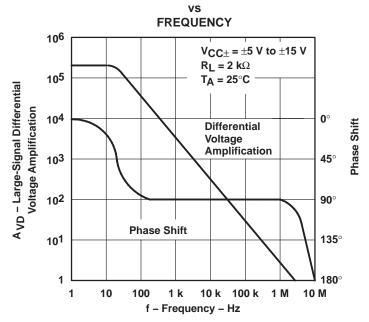


Figure 12

NORMALIZED UNITY-GAIN BANDWIDTH AND PHASE SHIFT

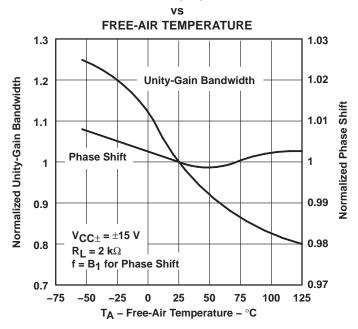


Figure 13

[†]Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS[†]

COMMON-MODE REJECTION RATIO FREE-AIR TEMPERATURE 89 $V_{CC\pm} = \pm 15 V$ CMRR - Common-Mode Rejection Ratio - dB $R_L = 10 \text{ k}\Omega$ 88 87 86 85 84 -75 -50 25 50 75 100 125 T_A – Free-Air Temperature – $^{\circ}C$

Figure 14

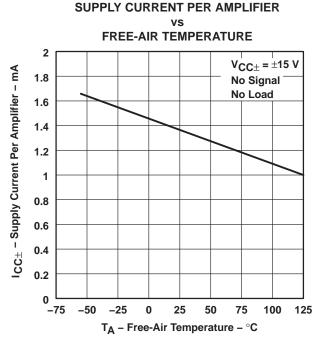


Figure 16

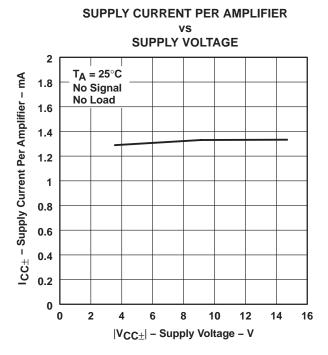
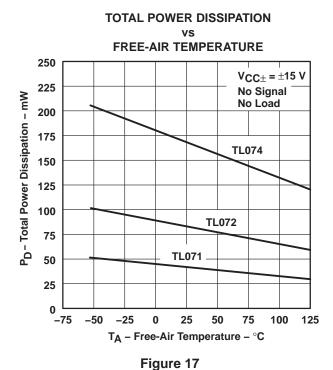


Figure 15



†Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



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TYPICAL CHARACTERISTICS

NORMALIZED SLEW RATE FREE-AIR TEMPERATURE 1.15 $V_{CC\pm} = \pm 15 V$ $R_L = 2 k\Omega$ 1.10 $C_{L} = 100 \text{ pF}$ Normalized Slew Rate - V/µs 1.05 1 0.95 0.90 0.85 -75 -50 -25 50 100 125

Figure 18

 T_A – Free-Air Temperature – $^{\circ}C$

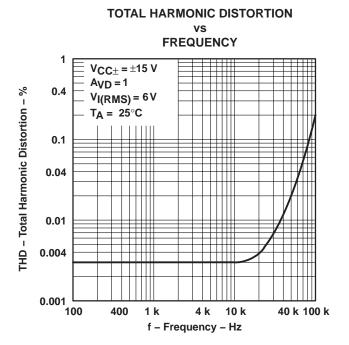


Figure 20

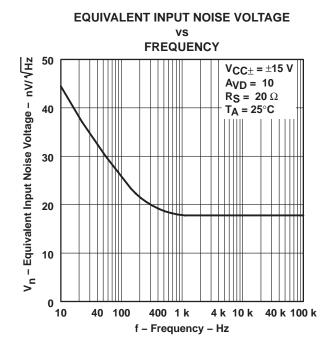


Figure 19

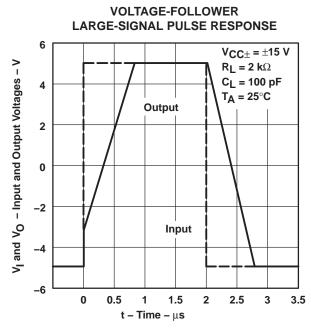


Figure 21



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TYPICAL CHARACTERISTICS

OUTPUT VOLTAGE ELAPSED TIME 28 24 Overshoot V_O - Output Voltage - mV 20 90% 16 12 8 4 10% $V_{CC\pm}$ = ±15 V $R_L = 2 k\Omega$ 0 T_A = 25°C 0.2 0.3 0.4 0.5 0.6 $\textbf{t-Elapsed Time-} \mu \textbf{s}$

Figure 22



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APPLICATION INFORMATION

Table of Application Diagrams

APPLICATION DIAGRAM	PART NUMBER	FIGURE
0.5-Hz square-wave oscillator	TL071	23
High-Q notch filter	TL071	24
Audio-distribution amplifier	TL074	25
100-kHz quadrature oscillator	TL072	26
AC amplifier	TL071	27

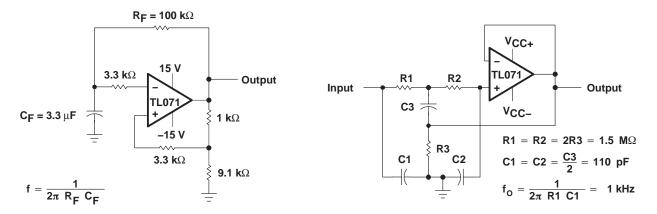


Figure 23. 0.5-Hz Square-Wave Oscillator

Figure 24. High-Q Notch Filter

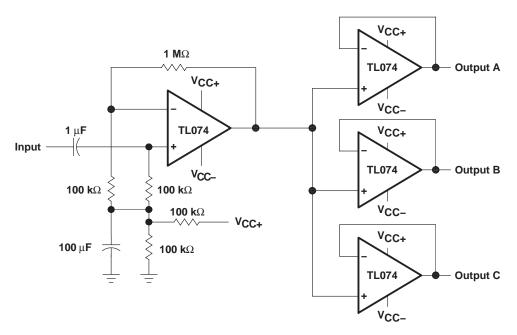
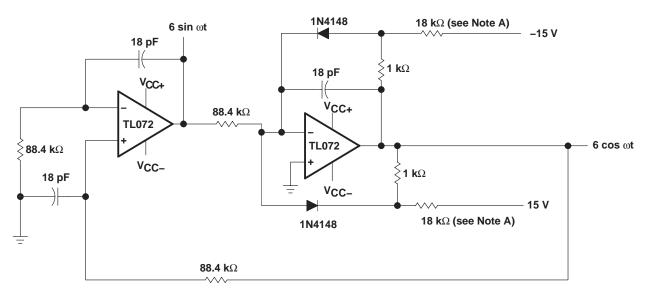


Figure 25. Audio-Distribution Amplifier



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APPLICATION INFORMATION



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 26. 100-kHz Quadrature Oscillator

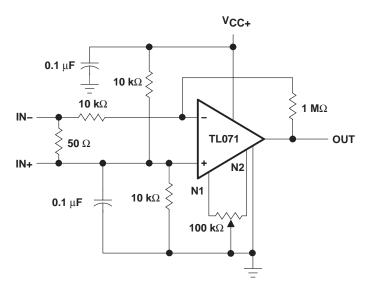


Figure 27. AC Amplifier





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
8102304HA	OBSOLETE			10		TBD	Call TI	Call TI
81023052A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8102305HA	ACTIVE	CFP	U	10	1	TBD	A42 SNPB	N / A for Pkg Type
8102305PA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
81023062A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8102306CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8102306DA	ACTIVE	CFP	W	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/11905BPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/11906BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL071ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071BCP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071BCPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
TL071CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TL071ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL071IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL071IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL071MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL071MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL071MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL072ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL072ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL072ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL072ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL072ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL072ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL072BCP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072BCPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL072CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS &	CU NIPDAU	Level-2-260C-1YEAR





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽
						no Sb/Br)		
TL072CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
TL072CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAF
TL072CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAF
TL072CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAF
TL072CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072CPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
TL072CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL072CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL072CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
TL072CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
TL072ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEA
TL072IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEA
TL072IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEA
TL072IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEA
TL072IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEA
TL072IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEA
TL072IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL072MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL072MJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL072MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL072MUB	ACTIVE	CFP	U	10	1	TBD	A42 SNPB	N / A for Pkg Type
TL074ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
TL074ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
TL074ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
TL074ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL074ACJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL074ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074ACNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ACNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074BCNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074BCNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074CNSR	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
TL074CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)		Level-1-260C-UNLIM
TL074CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074ID	ACTIVE	SOIC	D	14	50	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
TL074IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL074IJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL074IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL074MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL074MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL074MJ	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL074MJB	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL074MWB	ACTIVE	CFP	W	14	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

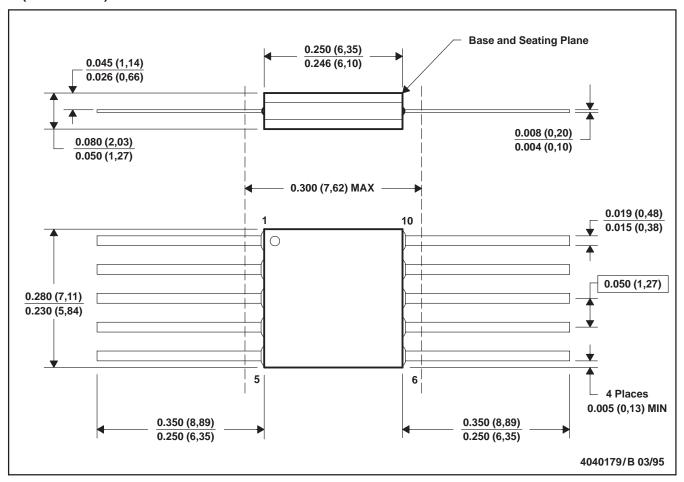
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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